

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of the Claims:

1. (Previously Presented) An apparatus, comprising:

an evaporator section of a heat pipe attached to a first end of a base of the heat pipe, wherein a width of the evaporator section is greater than a width of the base, and the evaporator section having a size of at least a surface area of a heat spreader.
2. - 4. (Cancelled)
5. (Original) The apparatus of Claim 1, further comprising:

a heat dissipator attached to a second end of the base.
6. (Previously Presented) The apparatus of Claim 5, further comprising:

a plurality of fins formed of the second end of the base, the plurality of fins attached to a bottom surface of the heat dissipator, the fins having a length approximately equal to the width of the base.

7. (Cancelled)
8. (Withdrawn) An apparatus, comprising:
 - a base formed of a heat conductive material, the base having a first end and a second end;
 - a heat absorber attached to the first end of the base, the heat absorber having a first width greater than a second width of the base, the heat absorber having a top surface and a planar bottom surface, the planar bottom surface having a first surface area approximately equal to a second surface area of an integrated heat spreader attached to a silicon die; and
 - a heat dissipator attached to the second end of the base.
9. (Withdrawn) The apparatus of Claim 8, wherein the heat dissipator has a third width approximately equal to the second width of the base.
10. (Withdrawn) The apparatus of Claim 8, further comprising:
 - a plurality of fins formed of the heat conductive material, the plurality of fins attached to a bottom surface of the heat dissipator, the plurality of fins having a length approximately equal to the second width of the base.
11. (Withdrawn) The apparatus of Claim 10, wherein the heat conductive material is a material selected from the group consisting of copper, a copper alloy, or aluminum.

12. (Withdrawn) The apparatus of Claim 8, wherein the heat conductive material is copper.

13. (Previously Presented) A computer system, comprising:

a central processing unit (CPU);

and

an evaporator section of a heat pipe attached to a first end of a base of the heat pipe, wherein a width of the evaporator section is greater than a width of the base, and the evaporator section having a size of at least a surface area of a heat spreader.

14-15. (Cancelled)

16. (Original) The computer system of Claim 13, further comprising:

a heat dissipator attached to a second end of the base.

17. (Previously Presented) The computer system of Claim 16, further comprising:

a plurality of fins formed on the second end of the base, the plurality of fins attached to a bottom surface of the heat dissipator, the plurality of fins

having a length approximately equal to the width of the base.

18. (Cancelled)